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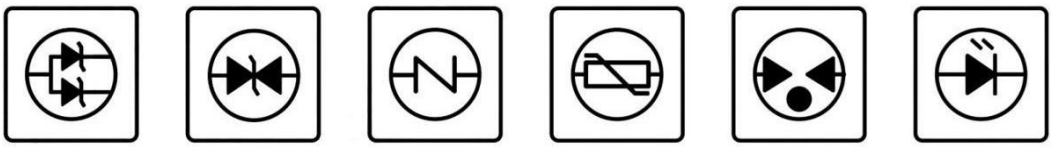
SEMICONDUCTOR



LESD3Z5.0C-MS

Product specification

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FEATURES

- IEC61000-4-2 (ESD) ±8kV (Contact), ±15kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ηs)
  Peak power dissipation: 60W (8/20μs)
- Protects one I/O line
- Low clamping voltage
- Working voltages : 5V
- Low leakage current

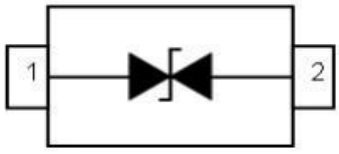
MACHANICAL DATA

- SOD-323 package
- Terminals: Tin plated, solderable per MIL-STD-750, method 2026
- Packaging: Tape and Reel
- Reel size: 7 inch

APPLICATIONS

- High Speed Line :USB1.0/2.0, VGA, DVI, SDI
- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
 SOD-323		3M*

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ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±30 ±30	kV
P_{PP}	Peak Pulse Power (8/20μs)	60	W
T_{OPT}	Operating Temperature	-55~150	OC
T_{STG}	Storage Temperature	-55~150	OC

ELECTRICAL CHARACTERISTICS (Tamb=25℃)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				5.0	V
V_{BR}	Reverse Breakdown Voltage	I_T = 1mA	5.6		7.8	V
I_R	Reverse Leakage Current	V_{RWM} = 5V			1.0	μA
V_C	Voltage	I_{PP} = 5A, t_p = 8/20μs			12.0	V
C_J	Junction Capacitance	V_R = 0V, f = 1MHz			18	pF

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ELECTRICAL CHARACTERISTICS CURVE

Fig 1 8/20μs Waveform per IEC61000-4-5

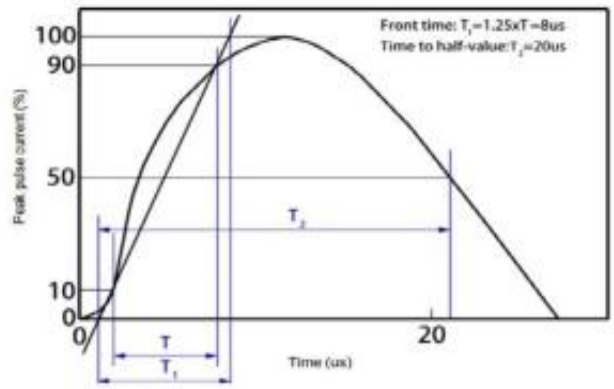


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

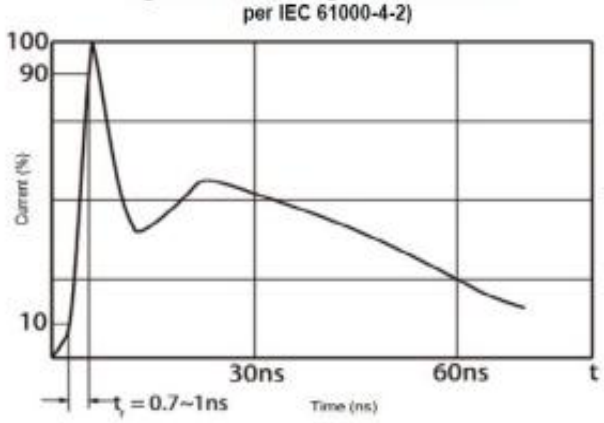


Fig 3 Power Derating Curve

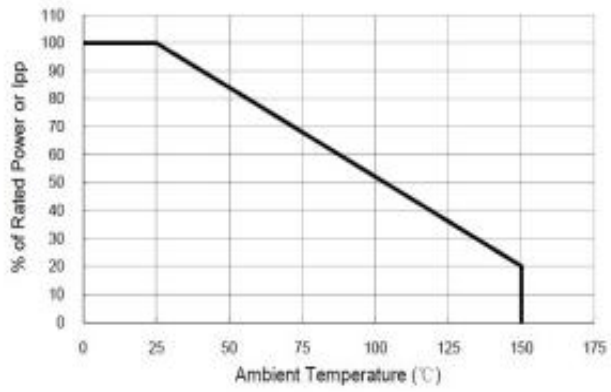


Fig 4 Voltage vs Capacitance

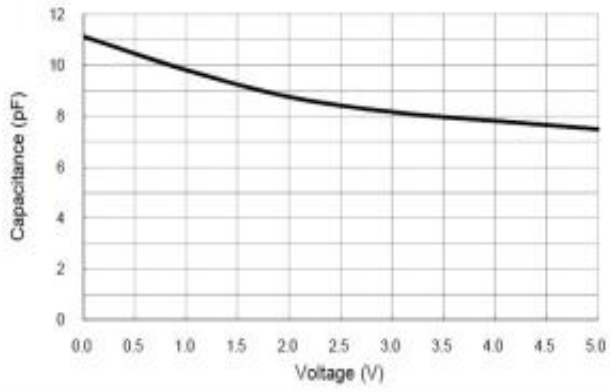


Fig 5 Voltage Sweeping

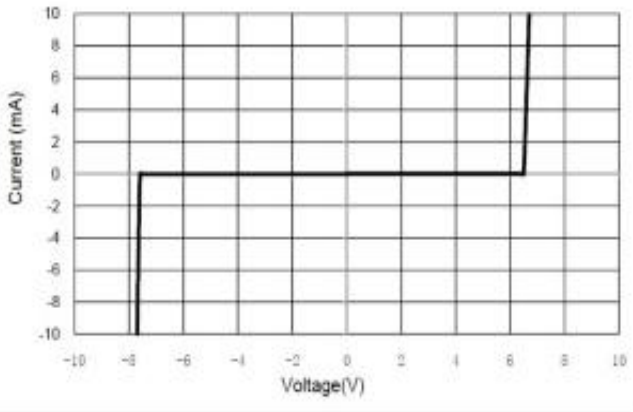
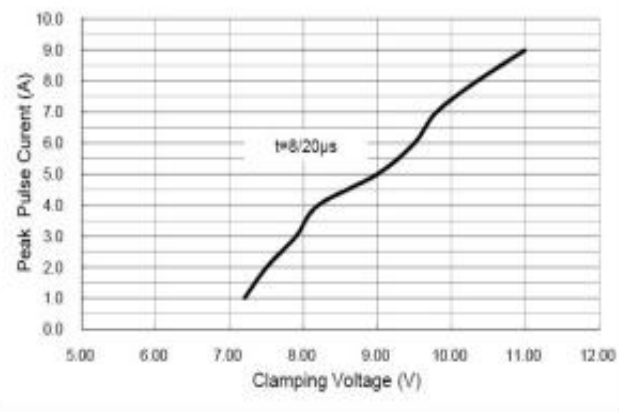


Fig 6 Clamping Voltage vs Peak Pulse Current



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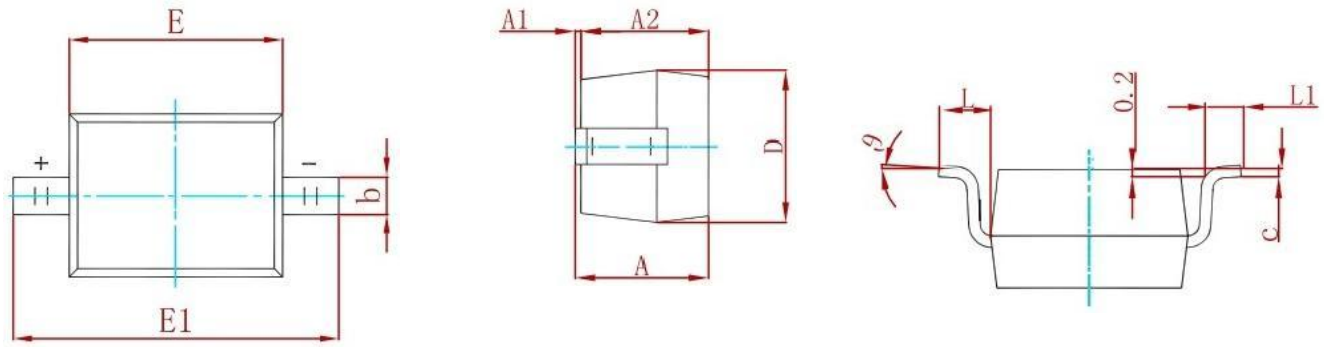
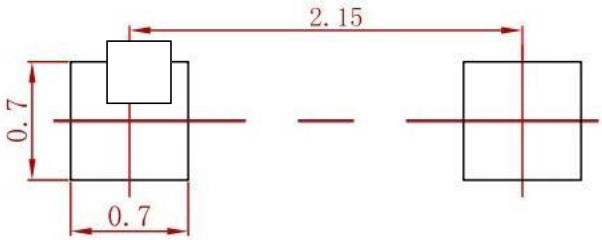
PACKAGE MECHANICAL DATA



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min.	Max
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
C	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF		0.019 REF	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
LESD3Z5.0C-MS	SOD-323	3000

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